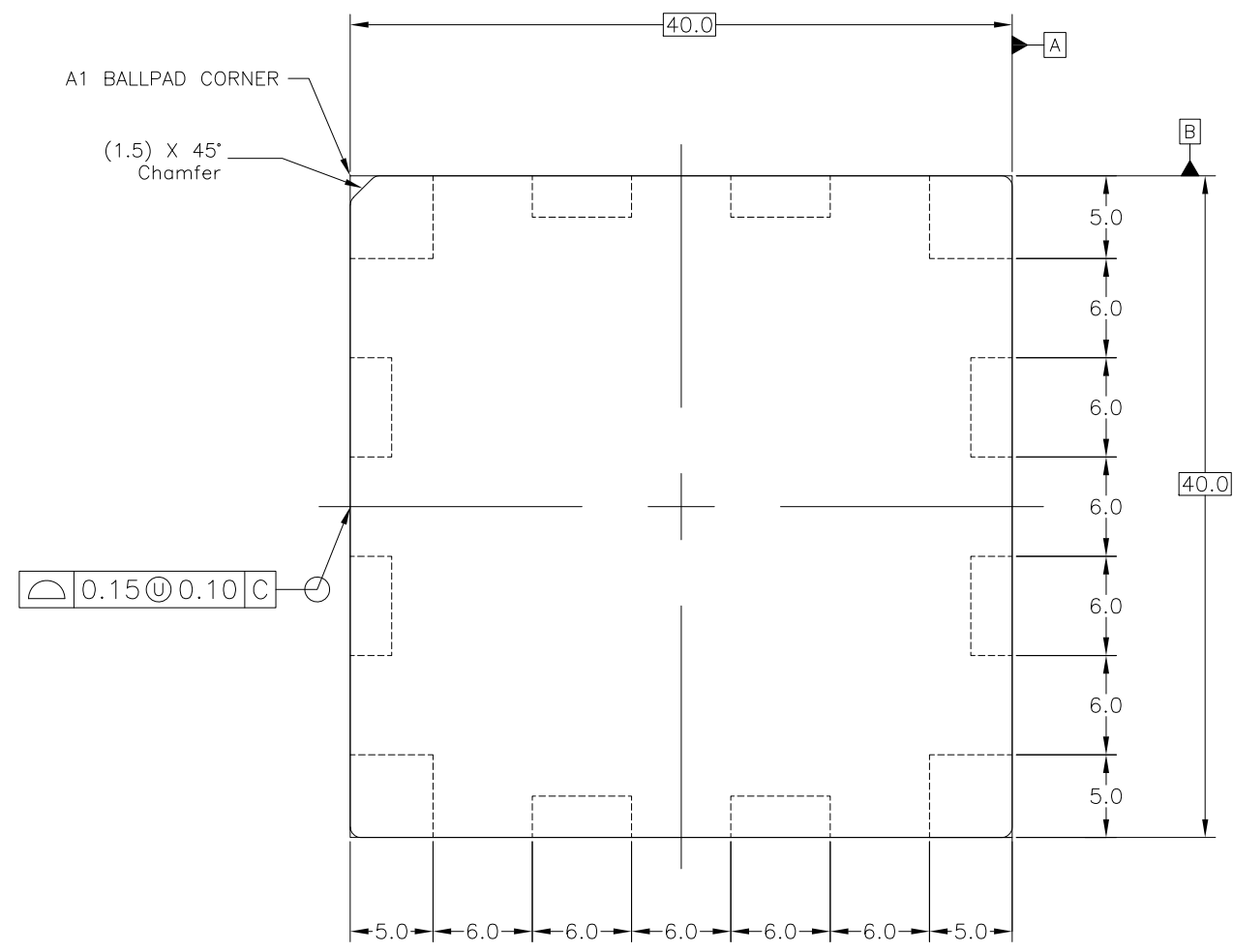
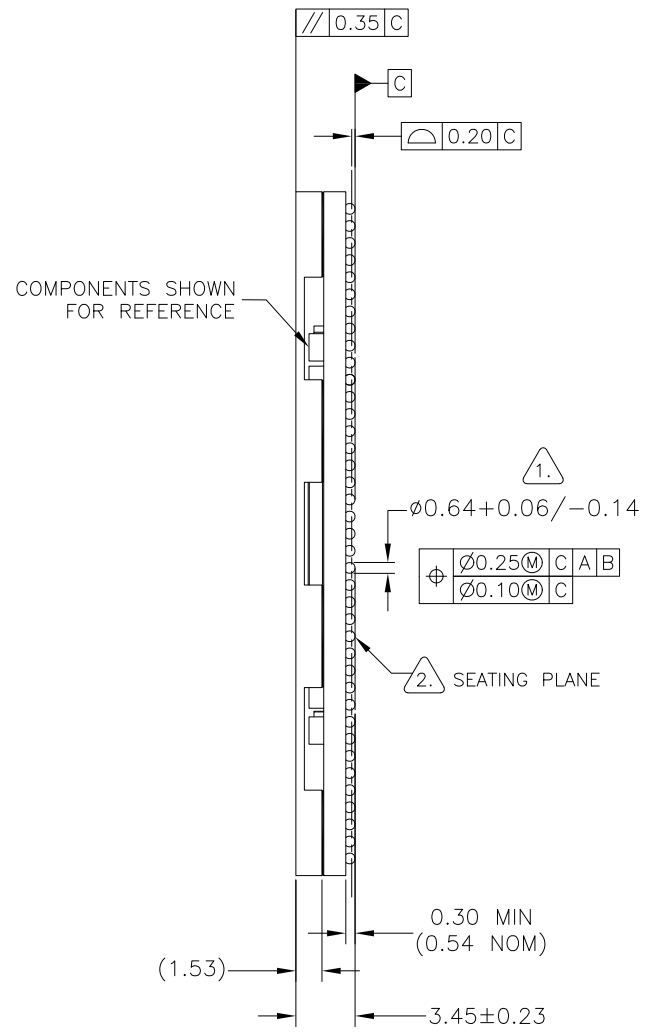


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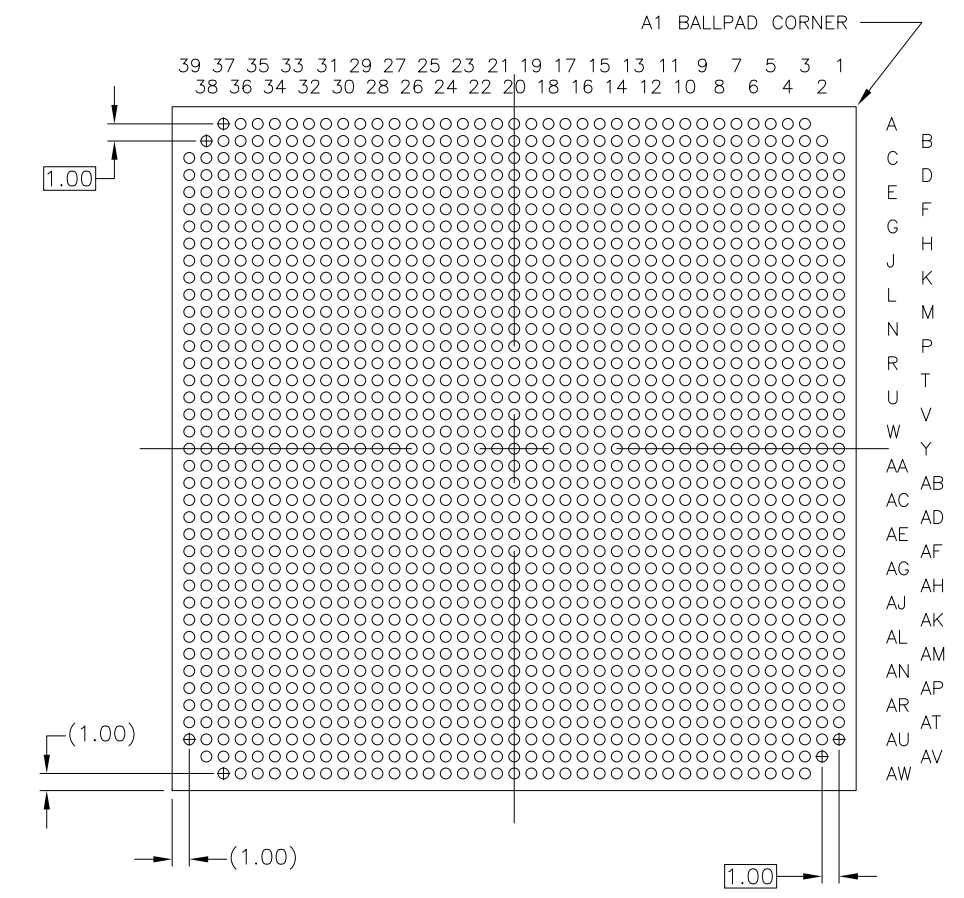
ECN NO.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
20250050	0	New release	03/05/2025	Erwin Q.
20250364	1	Updated package height with tolerance, added RTPFS460ZT-FC1509	09/23/2025	Tyler J.
20260061	2	Removed die outline in top view.	03/02/2026	Tyler J.



TOP VIEW



SIDE VIEW



BOTTOM VIEW  
1509 Solder Balls

NOTES: UNLESS OTHERWISE SPECIFIED

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-2009.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

<b>GENERAL TOLERANCE</b> X.X ± 0.01 X.XX ± 0.05 X.XXX ± 0.03 ANGULAR ± 0.01° UNLESS OTHERWISE SPECIFIED INTERPRET DIM AND TOL PER ASME Y14.5M - 2009	<b>PROJECTION</b> 		<b>MICROCHIP</b> Microchip Technology Inc., FPGA Business Unit 3850 N. 1st St. San Jose, CA 95134						
	<b>APPROVALS</b> DRAWN: Erwin Quiobo CHECKED: _____ ENG'R: _____ RELEASED: _____		<b>DATE</b> 03/05/2025		<b>TITLE:</b> RTPF500ZT-FC1509, RTPFS460ZT-FC1509 PACKAGE OUTLINE DWG <b>PKG. TYPE:</b> 40.0 mm X 40.0 mm, 1.0 mm BALL PITCH, 1509 SOLDER BALLS, FLIP CHIP BGA				
<b>DIMENSIONS:</b> Millimeters [inches] unless specified		<b>CHECKED</b> _____		<b>MICROCHIP PART NUMBER:</b> ---		<b>MICROCHIP DWG. NUMBER:</b> 1-14-12107		<b>REV</b> 2	
		<b>ENG'R</b> _____		<b>SIZE</b> B		<b>VENDOR NAME:</b> N/A		<b>VENDOR PART NUMBER:</b> ---	
		<b>RELEASED</b> _____				<b>SCALE:</b> NONE		<b>SHEET 1 OF 1</b>	

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